



This is a multi-site certificate, additional site(s) are listed on the next page(s)

13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-8580, Japan

Bureau Veritas Certification Holding SAS -UK Branch certifies that the Management System of the above organisation has been audited and found to be in accordance with the requirements of the management system standards detailed below

ISO9001:2015, JIS Q 9001:2015

Scope of certification

- Design / development, manufacturing, installation / maintenance services and supply of service partsof precision processing machines and systems for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafers and other materials.
- Design / development and manufacturing of abrasive cut-off wheels.
- · Supply of precision processing services.
- · Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Original cycle start date:

11 AUGUST 1995

Expiry date of previous cycle:

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Recertification Audit date:

05 JULY 2024

Recertification cycle start date:

05 AUGUST 2024

Subject to the continued satisfactory operation of the organisation's Management System,

this certificate expires on:

10 AUGUST 2027

Certificate No. 22082636

Version: 1.0

Revision date: 05 AUGUST 2024





0008

Certification body address: 5th Floor, 66 Prescot Street, London, E1 8HG, United Kingdom

Local office: Bureau Veritas Japan Co., Ltd. Certification Division

KRC bldg. 8F, 18, Nihon-odori, Naka-ku, Yokohama, 231-0021, Japan

Further clarifications regarding the scope of this certificate and the applicability of the management system requirements may be obtained by consulting the organisation.







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- · Supply of precision processing services.
- · Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO Corporation Head Office	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-8580, Japan	Design / development and sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Design / development and sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Design / development and sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. Supply of precision processing services.
Kure Plant	1-23, Hiro Bunka-cho, Kure-shi, Hiroshima, 737-0198, Japan	Manufacturing and sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Design / development, manufacturing and sales of abrasive cut-off wheels.

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- · Supply of precision processing services.
- · Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Kuwabata Plant	4010-1, Gohara-cho, Kure-shi, Hiroshima, 737-0161, Japan	 Design / development and manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Design / development and manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Manufacturing of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.
Chino Plant	480, Toyohira, Chino-shi, Nagano, 391-0297, Japan	 Design / development and manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Manufacturing of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials.

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- · Supply of precision processing services.
- · Supply of on-site electronics processing services.
- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
Osaka Branch Office	3-16, Senba-higashi 3-chome, Minoh-shi, Osaka, 562-0035, Japan	 Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. Sales of abrasive cut-off wheels.
Kyushu Branch Office	2170-4, Tabaru, Mashiki-machi, Kamimashiki-gun, Kumamoto, 861-2202, Japan	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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Site Name	Site Address	Site Scope
Sendai Branch Office	5-1, Honcho 2-chome, Aoba-ku, Sendai-shi, Miyagi, 980-0014, Japan	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.
DISCO HI-TEC TAIWAN CO., LTD.	1F, 9F., No.188, Baoqiao Rd., Xindian Dist., New Taipei City, Taiwan (R.O.C.)	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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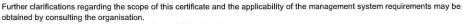




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Site Name	Site Address	Site Scope
DISCO HI-TEC AMERICA, INC.	5921 Optical Ct., San Jose, CA 95138, U.S.A.	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. Supply of precision processing services.
DISCO HI-TEC (SINGAPORE) PTE LTD	80 Ubi Avenue 4, #06-01 Singapore 408831	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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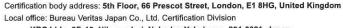
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- Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.

Site Name	Site Address	Site Scope
DISCO HI-TEC EUROPE GmbH	Liebigstrasse 8, D-85551 Kirchheim b. Muenchen, Germany	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials. Supply of precision processing services.
DISCO HI-TEC KOREA Corporation	3F, DHK Solution Bldg., 28, Pangyo-ro 255beon-gil, Bundang-gu, Seongnam-si, Gyeonggi-do, Korea 13486	Sales, installation / maintenance services, and supply of service parts of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials. Sales of precision processing tools for cutting, grinding and polishing of silicon wafer and other materials. Sales of functional consumables (assisting materials) for cutting, grinding and polishing of silicon wafer and other materials.

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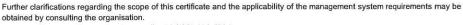




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Site Name	Site Address	Site Scope
DISCO KKM FACTORIES, LTD.	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-0016, Japan	Supply of on-site electronics processing services.
DAIICHI COMPONENTS, LTD. HEAD OFFICE	13-11, Omori-Kita 2-chome, Ota-ku, Tokyo, 143-0016, Japan	Sales of various types of power sources, power generators, and motors.
DAIICHI COMPONENTS, LTD. CHINO PLANT	480, Toyohira, Chino-shi, Nagano, 391-0294, Japan	Design / development, manufacturing, repair, and supply of maintenance parts of various types of power sources, power generators, and motors.
DISCO Manufacturing Corporation Hiroshima Works	2507-913, Gohara-cho, Kure-shi, Hiroshima, 737-0161, Japan	Manufacturing of precision processing machines and systems for cutting, grinding and polishing of silicon wafer and other materials.

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